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**COOL-BOND**  
**CB8130**

**Medium Strength Adhesive**  
**"Phase-Change" Dry Pad**  
**Melt-Flow >200°C @ <3 psi**  
**High Thermal Conductivity**  
**High Electrical Conductivity**

**IDEAL FOR:**

- Silicone Thermal Gasket Replacement
- Thermal Grease Replacement
- Medium Strength Reworkable Adhesive

**DESCRIPTION:**

CB8130 is a silver filled, electrically conductive, medium bond strength adhesive designed to enhance thermal and electrical transfer from die/wafer to heat-sink during burn-in testing. CB8130 has good thermal conductivity and is dry for easy handling at room temperature. It can be die-cut into any shape or size for power transistors and components. The medium bond strength is applicable up to 110°C.

When a power device goes into operation and generates heat in excess of 190°C, CB8130 will "melt" or "reflow" to form intimate interfaces between the contact surfaces and thus dramatically reduces the thermal and electrical impedance. It provides grounding and cooling for the heat generating devices.

**AVAILABILITY:**

CB8130 is available in sheet sizes or as custom preforms. Standard thicknesses are 0.003" and 0.006". Special thicknesses are available.

**APPLICATION PROCEDURES:**

- ( 1 ) Keep product at room temperature for 15 minutes before using.
- ( 2 ) Cut or pre-cut to desired size and shape.
- ( 3 ) Place conductive COOL-BOND between device and heat-sink.
- ( 4 ) Clamp with suitable force of more than 3 psi.

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 25°C/ 1s is )	<4X10 <sup>-4</sup> ohm-cm
Dielectric Strength (Volts/mil)	
Glass Transition Temp.(°C)	-55
Lap-Shear Strength	<400 psi <2.8 N/mm <sup>2</sup>
Device Push-off Strength	>400 psi >2.8 N/mm <sup>2</sup>
Hardness (Type)	40 (A)
Cured Density (gm/cc)	4.5
Thermal Conductivity	>55 Btu-in/hr-ft <sup>2</sup> -°F >7.9 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	110
Maximum Continuous Operation Temp. (°C)	150

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**Melt/Flow:Conditions**

Temperature	Time	Pressure
>200°C	0.5 sec	<3 psi
>130°C	0.5 sec	>3 psi

**SHELF LIFE:**

Storage temperature	Shelf Life
0-5°C	1 yr
	in sealed package

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer to MSDS for more details.

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